

APPROVAL SHEET

KFDIP Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC DIPLEXER

Halogens Free Product

2.4 GHz & 5 GHz ISM Band RF Application

P/N: KFDIP2004L197B1U

*Contents in this sheet are subject to change without prior notice.

FEATURES

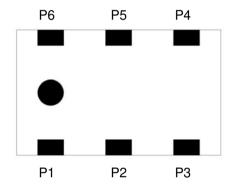
- 1. Miniature footprint: 2.0 X 1.25 X 0.4 mm³.
- 2. LTCC Process
- 3. Low Profile Thickness
- 4. Low Insertion Loss
- 5. High Rejection
- 6. RoHS Compliance
- 7. Halogens Free Product

APPLICATIONS

1. 2400 ~ 2500 MHz and 4900 ~ 5950 MHz working frequency

CONSTRUCTION

Top view



PIN	IN Connection		Connection
1	GND	4	Higher Freq. Port
2	Common(ANT) Port	5	GND
3	GND	6	Lower Freq. Port

DIMENSIONS

	Figure	Symbol	Dimension (mm)
W	Е т	L	2.00 ± 0.15
	A	W	1.25 ± 0.15
	(C)	Т	0.40 ± 0.10
→ ■ ■		А	0.20 ± 0.15
		В	0.30 ± 0.15
		С	0.35 ± 0.15
Top view	Bottom view Side view	D	0.65 ± 0.15
		E	0.20 ± 0.15



ELECTRICAL CHARACTERISTICS

KFDIP2004L197B1U	Specification			
Frequency range	2400 ~ 2500 MHz	4900 ~ 5950 MHz		
Insertion Loss	0.6 dB max. (0.45 dB typ.)	1.0 dB max. (0.82 dB typ.)		
		20 dB min. (29.1 dB typ.) @ 824 ~ 915 MHz		
	15 dB min. (17.7 dB typ.) @ 3600 MHz	18 dB min. (22.1 dB typ.) @ 1800 ~ 2500 MHz		
Attenuation	25 dB min. (25.3 dB typ.) @ 4800 ~ 5000 MHz	14 dB min. (21.6 dB typ.) @ 3000 ~ 3900 MHz		
	20 dB min. (32.8 dB typ.) @ 7200 ~ 7500 MHz	20 dB min. (27.7 dB typ.) @ 9800 ~ 11900 MHz		
		20 dB min. (29.5 dB typ.) @ 14700 ~ 17850 MHz		
Isolation	20 dB min. (22.4 dB typ.) @ DC ~ 2500 MHz			
Isolation	20 dB min. (26.6 dB typ.) @ 4900 ~ 5950 MHz			
Return Loss	10 dB min. (12.6 dB typ.)			
Moisture sensitivity levels	vity levels LEVEL 1 (Refer to : IPC/JEDEC J-STD-020)			

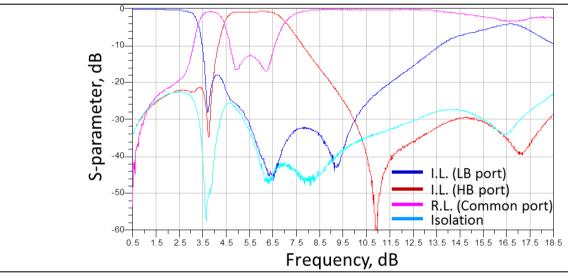
Operating & Storage Condition (Component)

Operation Temperature Range: -40 \sim +85 $^{\circ}$ C Storage Temperature Range: -40 \sim +85 $^{\circ}$ C

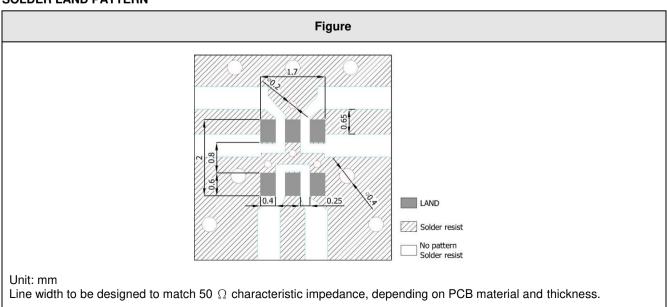
Storage Condition before Soldering (Included packaging material)

Storage Temperature Range: $+5 \sim +40$ $^{\circ}$ C Humidity: 30 to 70% relative humidity

Typical Electrical Chart



SOLDER LAND PATTERN





RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability	*Solder bath temperature : 235 \pm 5°C	At least 95% of a surface of each terminal
JIS C 0050-4.6	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
JESD22-B102D	Solder : Sn3Ag0.5Cu for lead-free	
Leaching	*Solder bath temperature : 260 ± 5°C	Loss of metallization on the edges of each
(Resistance to	*Leaching immersion time : 30 \pm 0.5 sec	electrode shall not exceed 25%.
dissolution of	Solder : SN63A	Silver of their field oxocod 20%.
metallization)		
IEC 60068-2-58		
Resistance to soldering heat	*Preheating temperature : 120~150℃,	No mechanical damage.
JIS C 0050-5.4	1 minute.	Electrical specification shall satisfy the
	*Solder temperature: 270±5°C	descriptions in electrical characteristics under
	*Immersion time: 10±1 sec	the operational temperature range within -40
	Solder: Sn3Ag0.5Cu for lead-free	~ 85°C.
		Loss of metallization on the edges of each
	Measurement to be made after keeping at	electrode shall not exceed 25%.
	room temperature for 24±2 hrs	
Drop Test	*Height: 75 cm	No mechanical damage.
JIS C 0044	*Test Surface : Rigid surface of concrete or	Electrical specification shall satisfy the
Customer's specification.	steel.	descriptions in electrical characteristics under
	*Times: 6 surfaces for each units; 2 times	the operational temperature range within -40
	for each side.	~ 85°C.
	101 04511 01401	
Vibration	*Frequency: 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude: 1.5mm	Electrical specification shall satisfy the
	*Test times : 6hrs.(Two hrs each in three	descriptions in electrical characteristics under
	mutually perpendicular directions)	the operational temperature range within -40
		~ 85°C.
Adhesive Strength	10 · · · ·	
of Termination	*Pressurizing force :	No remarkable damage or removal of the
JIS C 0051- 7.4.3	5N(≤0603) ; 10N(>0603)	termination.
Bending test	*Test time: 10±1 sec	
JIS C 0051- 7.4.1	The middle part of substrate shall be	No mechanical damage.
010 0 0001 7.4.1	pressurized by means of the pressurizing rod	Electrical specification shall satisfy the
	at a rate of about 1 mm/s per second until the	descriptions in electrical characteristics under
	deflection becomes 1mm/s and then pressure	the operational temperature range within -40
	shall be maintained for 5±1 sec.	~ 85°C.
	Measurement to be made after keeping at	
	room temperature for 24±2 hours	

Temperature cycle JIS C 0025 High temperature	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

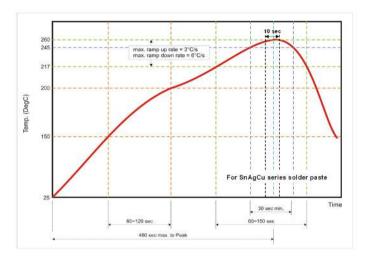


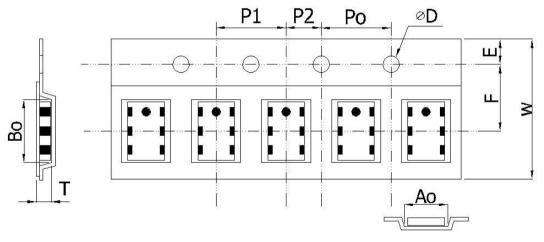
Fig 2. Infrared soldering profile

ORDERING CODE

KF	DIP	20	04	L	197B1U
Walsin	Product	Dimension code	Dimension code	Application	Specification
RF device	Code	Per 2 digits of Length, Width,:	04=	L:	Design code
	DIP: Diplexer	e.g. :	Thickness 04	2.4GHz/5GHz	
		20 =			
		Length 20,			
		Width 12,			

Minimum Ordering Quantity: 2000 pcs per reel.

PACKAGING

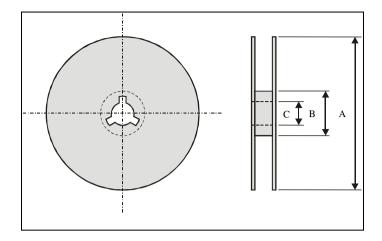


Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.40 ± 0.10	2.25 ± 0.10	1.55 ± 0.05	0.75 ± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05



Reel dimensions



Index	Α	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

Temperature : +5 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.